

AZ 40XT-11D – run sheet

Merck KGaA, Darmstadt, Germany

[nanyte.com/photoresists/az-40xt](https://www.merck.com/materials/nanyte.com/photoresists/az-40xt) · last updated 2026-07-26

Thickness: 20–60 µm

Softbake: 125 °C (115–125 °C) · hotplate

Exposure dose: 400 mJ/cm² @ 365 nm

Post-exposure bake: 105 °C (100–110 °C)

Develop: Developer AZ 300MIF · Dilution undiluted (ready-to-use 0.26N / 2.38% TMAH developer; no dilution ratio stated) · Time 4 min · Method puddle

Hardbake: 80 °C (80–85 °C) · 5 min